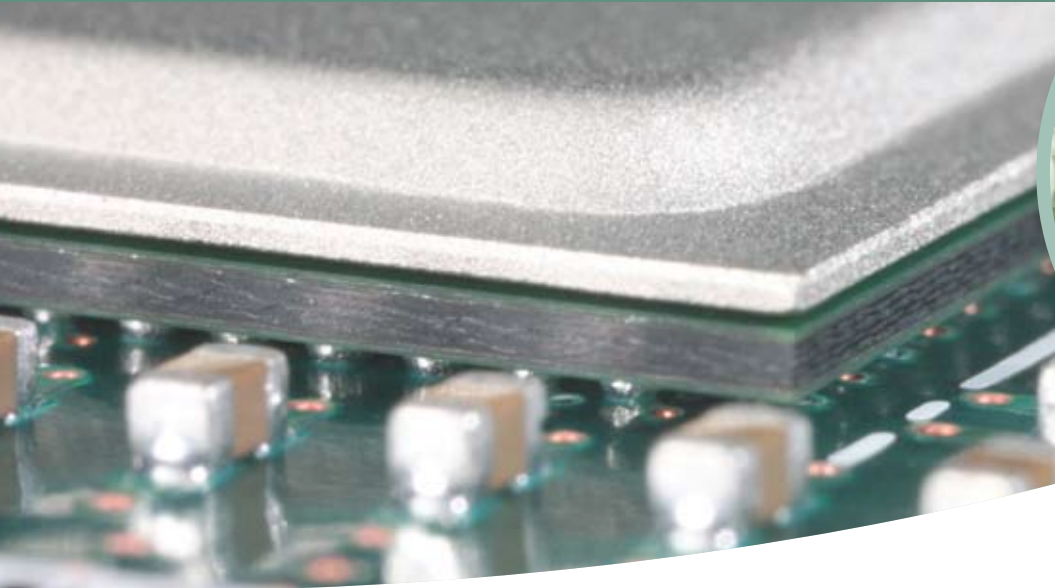


Complex Assembly Solutions

Shenzhen, China



Assembly Solutions Expertise

EI merges engineering, manufacturing, product reliability and life cycle support expertise into assembly solutions that not only exceed your expectations, but also surpass industry standards. The power of our solutions lie in the ability to provide you with a breadth of products and services. We can build your prototypes, design a process to address a new technology, handle your assembly challenges, and then develop and execute in-circuit or functional tests. Through the broad depth of our knowledge and experience, we will help you launch your product domestically and then boost your profitability during volume production with our low cost capability in Shenzhen, China.

EI delivers a unique mix of leading edge technology and technical expertise that gives our customers a time-to-market advantage and competitive differentiation. Our solutions support the needs of the information technology, telecommunications and advanced test equipment markets where highly reliable products built in robust manufacturing operations are essential to success.

Features

Production of a wide range of products from high-end, complex assemblies to lower complexity, support PCB assemblies

Full hybrid assembly, backplane, chassis and system build

Outstanding service and on-time delivery performance that consistently rates 99% or better

Extensive quality and process controls integrated within all our business processes, including:

Traceability system tracks/documents components and materials throughout each product's manufacture

Comprehensive process capabilities such as stencil design, automated solder inspection, X-ray examination, cleaning, rework/repair methods

Extensive test development and execution capabilities including FHP, ICT, and FCT using both industry accepted and EI developed protocols, methods and equipment

Leading edge assembly process development

Flexible, competitive supply chain management capabilities integrated into our execution model

Outstanding life cycle support includes analysis, repair and upgrade, testing and more

Complex Assembly Solutions



Capabilities - El Shenzhen Facility

Maximum Assembly Size

18" x 24" (457mm x 610mm) for SMT

18" x 24" (457mm x 610mm) for non-SMT backplanes

Technology

SMT

Press fit

Wave solder and selective PTH solder

Hand assembly and solder

Components

BGA/CGA down to 0.03" (0.8mm) pitch

Perimeter lead fine pitch to 10 mils

SMT discretes and chips down to 0402

Core Product Parametrics

High density hybrid assemblies
(average components >1500); double-sided,
complex boards with mixed technology

Hybrid assemblies (SMT/PTH/press fit)

Components: high I/O area array modules (CGA, PBGA)

Connectors: dense, high I/O connectors

Mechanical: cage, chassis, system assemblies

Testing

Genrad 2287

Functional system level

Certifications

IPC-A-610

For more detailed information about our complex assembly solutions, call us today at 866-820-4820. Our application engineers are ready to assist you with detailed information for successful design and build. You can also visit our website at www.endicottinterconnect.com.



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For more information, visit our website at www.endicottinterconnect.com